AL-01-B20 产品性能表

(Criterion: Typical value is based on specimen of 1.5mm AL \120μm dielectric just for reference.)

性能 PROPERTIES	测试方法 TEST METHOD	单位 UNIT	指标值 INDICATOR	典型值 TYPICAL VALUES
热性能 THERMAL PROPERTIES				
绝缘层热导率 Thermal conductivity	ASTM D5470	W/m.K	—	2.0
热阻 Thermal resistivity	ASTM D5470	℃*in²/W	—	0.085
玻璃化温度 Tg	DSC	℃	—	130
热分解温度 TD	TGA(Wt5%loss)	℃	≥360	380
最大操作温度 MOT	UL94	℃	—	130
热应力 Thermal stress	Solder floating 288℃	Minute	≥15	25
电性能 ELECTRICAL PROPERTIES				
体积电阻 Volume resistivity	IPC-TM-650 2.5.17	MΩ.cm	$\geq 10^6$	10^8
表面电阻 Surface resistivity	IPC-TM-650 2.5.17	MΩ	$\geq 10^4$	10^7
介电常数 Dielectric constant	IPC-TM-650 2.5.5.3	1MHz	—	4.8
耗损系数 Dissipation factor	IPC-TM-650 2.5.5.3	1MHz	—	≤0.02
击穿电压 Breakdown voltage	IPC-TM-650 2.5.6.2	AC/KV	—	5.0
耐电弧 Arc resistance	IPC-TM-650 2.5.1	S	≥60	120
机械性能 MECHANICAL PROPERTIES				
剥离强度 Peel strength	IPC-TM-650 2.4.8	Lb/in	≥8	8.5
吸水率 Moisture absorption	D-24/23 IPC-TM-650 2.6.2.1	%	≤1.5	0.5
机构评级&阻燃性 AGENCY RATINGS&DURABILITY				
U.L.可燃性 Flammability	UL94	Class	V-0	V-0
相对漏电起痕指数 CTI	IEC60112	V	≥600	600

高导热金属基覆铜板

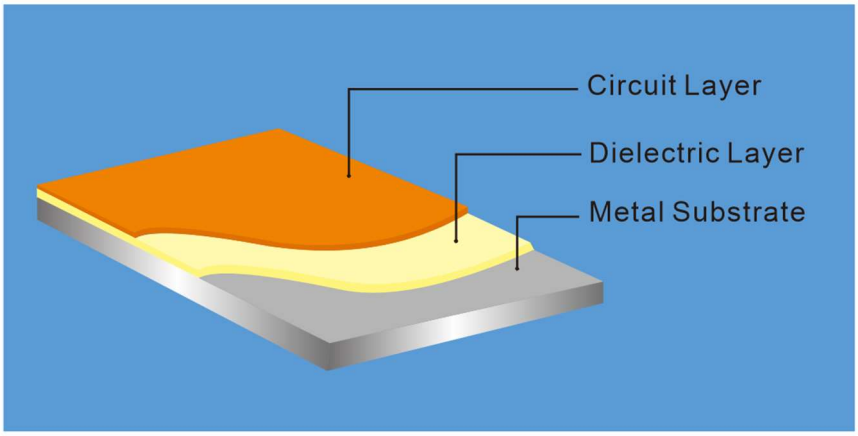
High Thermal Conductivity IMS CCL

产品介绍

Introduction of products

高导热金属基覆铜板能够针对不同的应用领域要求、各种铜厚、绝缘层特性、不同金属背板的需求，提供符合客户要求的高性价比产品。

For different areas of application requirements, various copper thickness, insulating layer characteristics and the need of different metal backboard, we can provide cost-effective metal based copper clad laminate with high thermal conductivity that meet customers' requirements.



产品规格

Specification of products

Standard BOYU Material Overview			
Item	Tolerance	Type	AL-01-B20
Dielectric Thickness	± 10 μm	Standard	100、120、180
		Special	75
Base Copper （μm)	± 10% μm	Standard	35、70、105
		Special	140、210
Aluminum Thickness （mm)	± 0.02mm	Standard	0.5-3.0
		Special	3.0-5.0
Aluminum Type	N/A	Standard	1060、3003、5052
Lamiante Size(mm)	± 2mm	Standard	1000X1200、1050X1250
MOQ request	N/A	Above Special	Specified （MOQ 100sheet)
Remark：		Finish thickness=Aluminum Thickness +Thickness of Thermal Conductive+Base Copper	